

Title (en)
SEMICONDUCTOR COMPONENT AND METHOD FOR PRODUCING A SEMICONDUCTOR COMPONENT

Title (de)
HALBLEITERBAUELEMENT UND VERFAHREN ZUR HERSTELLUNG EINES HALBLEITERBAUELEMENTS

Title (fr)
COMPOSANT SEMI-CONDUCTEUR ET PROCÉDÉ DE FABRICATION D'UN COMPOSANT SEMI-CONDUCTEUR

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Application
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Abstract (en)
[origin: WO2012010400A1] The invention relates to a semiconductor component (1) comprising at least one optoelectronic semiconductor chip (2) and a connecting carrier (5) having a connecting surface (53) on which the semiconductor chip (2) is disposed. A reflective coating (4) and a limiting structure (3) are formed on the connecting carrier (5), wherein the limiting structure (3) at least partially encloses the semiconductor chip (2) in the lateral direction, and the reflective coating (4) at least partially extends in the lateral direction between a side surface (21) of the semiconductor chip and the limiting structure (3). The invention further relates to a method for producing a semiconductor component.

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